# Materials Declaration

| Package | TSSOP |
|---|---|
| Body Size | 6.1 mm |
| LeadCount | 48 |
| Option | Pb-Free |

**Molding Compound**

| Item | % of Compound | Weight (g) | PPM |
|---|---|---|---|
| Biphenyl resin | 9 | 8.80 E-03 | 45512 |
| SiO2 Filler | 85 | 8.31 E-02 | 429839 |
| Phenol Resin | 5 | 4.89 E-03 | 25285 |
| Antimony_Sb2O3 | 0.5 | 4.89 E-04 | 2528 |
| Brominated Resin | 0.5 | 4.89 E-04 | 2528 |

**Leadframe**

| Item | % of Leadframe | Weight (g) | PPM |
|---|---|---|---|
| Cu | 96.2 | 6.87 E-02 | 355446 |
| Ni | 3 | 2.14 E-03 | 11085 |
| Si | 0.65 | 4.64 E-04 | 2402 |
| Mg | 0.15 | 1.07 E-04 | 554 |

**Internal Leadframe Plating**

| Item | % of Plating | Weight (g) | PPM |
|---|---|---|---|
| Ag | 100 | 2.57 E-03 | 13287 |

**External Leadframe Plating**

| Item | % of Plating | Weight (g) | PPM |
|---|---|---|---|
| Sn | 100 | 4.23 E-03 | 21887 |

**Bond Wires**

| Item | % of Wire | Weight (g) | PPM |
|---|---|---|---|
| Au | 99.99 | 1.89 E-03 | 9753 |

**Chip**

| Item | % of Chip | Weight (g) | PPM |
|---|---|---|---|
| Si | 100 | 1.36 E-02 | 70235 |

**Die Attach**

| Item | % of Die Attach | Weight (g) | PPM |
|---|---|---|---|
| Resin | 25 | 4.67 E-04 | 2415 |
| Ag Filler | 75 | 1.40 E-03 | 7245 |

**Molding Compound**

| Item | PPM | Method |
|---|---|---|
| Pb | Not Detected | ICP AES |
| Cd | Not Detected | ICP AES |
| Hg | Not Detected | ICP AES |
| Cr+6 | Not Detected | DIN 53314 |
| PBB | Not Detected | SGS In-house Method |
| PBDE | Not Detected | SGS In-house Method |

**Die Attach Paste**

| Item | PPM | Method |
|---|---|---|
| Pb | <5 | ICP AES |
| Cd | <5 | ICP AES |
| Hg | <5 | ICP AES |
| Cr+6 | <5 | ICP AES |
| PBB | Not Detected | |
| PBDE | Not Detected | |

**Package Totals**

| Weight (g) | PPM |
|---|---|
| **1.93 E-01** | 1000000 |

AMK-RV-C

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability t
any inaccuracy of such information.

# Materials Declaration

| | |
|---|---|
| **Package** | TSSOP |
| **Body Size** | 6.1 mm |
| **LeadCount** | 48 |
| **Option** | Sn/Pb |

### Molding Compound

| Item | % of Compound | Weight (g) | PPM |
|---|---|---|---|
| Biphenyl resin | 9 | 8.80 E-03 | 45512 |
| SiO2 Filler | 85 | 8.31 E-02 | 429839 |
| Phenol Resin | 5 | 4.89 E-03 | 25285 |
| Antimony_Sb2O3 | 0.5 | 4.89 E-04 | 2528 |
| Brominated Resin | 0.5 | 4.89 E-04 | 2528 |

### Leadframe

| Item | % of Leadframe | Weight (g) | PPM |
|---|---|---|---|
| Cu | 96.2 | 6.87 E-02 | 355446 |
| Ni | 3 | 2.14 E-03 | 11085 |
| Si | 0.65 | 4.64 E-04 | 2402 |
| Mg | 0.15 | 1.07 E-04 | 554 |

### Internal Leadframe Plating

| Item | % of Plating | Weight (g) | PPM |
|---|---|---|---|
| Ag | 100 | 2.57 E-03 | 13287 |

### External Leadframe Plating

| Item | % of Plating | Weight (g) | PPM |
|---|---|---|---|
| Sn | 85 | 3.60 E-03 | 18604 |
| Pb | 15 | 6.35 E-04 | 3283 |

### Bond Wires

| Item | % of Wire | Weight (g) | PPM |
|---|---|---|---|
| Au | 99.99 | 1.89 E-03 | 9753 |

### Chip

| Item | % of Chip | Weight (g) | PPM |
|---|---|---|---|
| Si | 100 | 1.36 E-02 | 70235 |

### Die Attach

| Item | % of Die Attach | Weight (g) | PPM |
|---|---|---|---|
| Resin | 25 | 4.67 E-04 | 2415 |
| Ag Filler | 75 | 1.40 E-03 | 7245 |

### Package Totals

| Weight (g) | PPM |
|---|---|
| **1.93 E-01** | 1000000 |

### Molding Compound

| Item | PPM | Method |
|---|---|---|
| Pb | Not Detected | ICP AES |
| Cd | Not Detected | ICP AES |
| Hg | Not Detected | ICP AES |
| Cr+6 | Not Detected | DIN 53314 |
| PBB | Not Detected | SGS In-house Method |
| PBDE | Not Detected | SGS In-house Method |

### Die Attach Paste

| Item | PPM | Method |
|---|---|---|
| Pb | <5 | ICP AES |
| Cd | <5 | ICP AES |
| Hg | <5 | ICP AES |
| Cr+6 | <5 | ICP AES |
| PBB | Not Detected | |
| PBDE | Not Detected | |

AMK-RV-A

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability t
any inaccuracy of such information.